

AMENDED CLAIM SET:

1. (original) A semiconductor encapsulating epoxy resin composition comprising
 - (A) an epoxy resin,
 - (B) a phenolic resin curing agent,
 - (C) a molybdenum compound, and
 - (D) 300 to 900 parts by weight per 100 parts by weight of components (A) and (B) combined of an inorganic filler,
wherein nitrogen atoms are contained in component (A) and/or component (B) in an amount of 1.5 to 20% by weight based on the weight of components (A) and (B) combined.
2. (original) The epoxy resin composition of claim 1 wherein component (B) is a phenolic resin containing nitrogen atoms in its skeleton in the form of a triazine ring structure, guanamine skeleton or cyanurate skeleton.
3. (original) The epoxy resin composition of claim 1 wherein component (A) is an epoxy resin containing nitrogen atoms in its skeleton in the form of a triazine ring structure, guanamine skeleton or cyanurate skeleton.
4. (original) The epoxy resin composition of claim 1 wherein the molybdenum compound (C) is zinc molybdate.
5. (original) The epoxy resin composition of claim 2 wherein the molybdenum compound (C) is zinc molybdate supported on an inorganic filler.
6. (original) A semiconductor device encapsulated with a cured product of the epoxy resin composition of claim 1.

7. (previously presented) A semiconductor encapsulating epoxy resin composition comprising (A) an epoxy resin, (B) a phenolic resin curing agent, (C) a molybdenum compound, and (D) 300 to 900 parts by weight per 100 parts by weight of components (A) and (B) combined of an inorganic filler,

wherein nitrogen atoms are contained in component (B) in an amount of 2 to 8 weight-% based on the weight of components (A) and (B) combined.

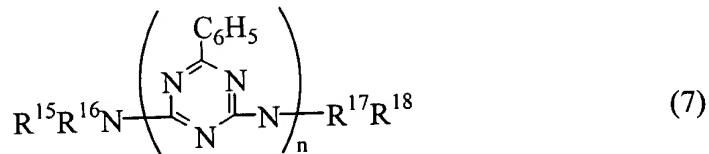
8. (previously presented) A semiconductor device encapsulated with a cured product of the epoxy resin composition of claim 7.

9. (previously presented) A method of improving the balance between flame retardance and hardness in a molded semiconductor encapsulating resin composition, which method comprises the step of formulating said composition to comprise (A) an epoxy resin, (B) a phenolic resin curing agent, (C) a molybdenum compound, and (D) 300 to 900 parts by weight per 100 parts by weight of components (A) and (B) combined of an inorganic filler, provided that nitrogen atoms are contained in component (B) in an amount of 1.5 to 20 weight-% based on the weight of components (A) and (B) combined.

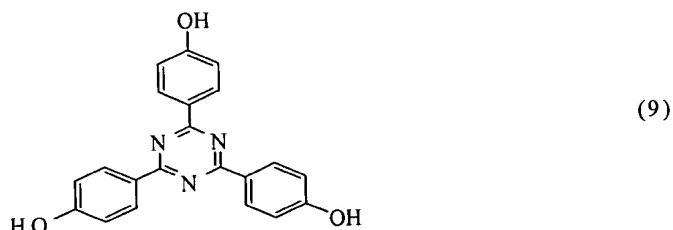
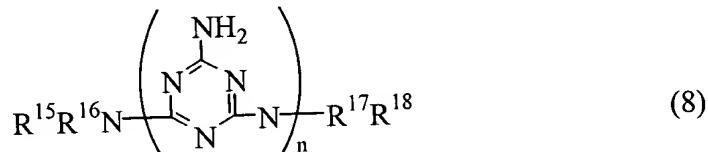
10. (previously presented) The method of claim 9, wherein the flame retardance of said molded composition when rated in accordance with UL-94 test specification is V-0 and wherein the hardness of said molded composition when measured in accordance with the method described in JIS-K6911 ranges from 75 to 85.

11. (new) A semiconductor encapsulating epoxy resin composition comprising
(A) an epoxy resin,
(B) a phenolic resin curing agent selected from the group consisting of (i) a phenol novolac resin having a benzoguanamine skeleton represented by formula (7), wherein R^{15} , R^{16} , R^{17} , and R^{18} are hydrogen or a phenol novolac resin having one free valence bond, with the

proviso that at least one of R^{15} , R^{16} , R^{17} , and R^{18} is a phenol novolac resin having one free valence bond, and n is an integer of 1 to 10 selected so as to give the phenolic hydroxyl equivalent of (b) and (c), (ii) a phenol novolac resin having melamine skeleton represented by



formula (8), wherein R^{15} , R^{16} , R^{17} , and R^{18} are hydrogen or a phenol novolac resin having one free valence bond, with the proviso that at least one of R^{15} , R^{16} , R^{17} , and R^{18} is a phenol novolac resin having one free valence bond, and n is an integer of 1 to 10 selected so as to give the phenolic hydroxyl equivalent prescribed above, and (iii) a phenolic resin represented by formula



(C) a molybdenum compound, and
(D) 300 to 900 parts by weight per 100 parts by weight of components (A) and (B) combined of an inorganic filler,
wherein nitrogen atoms are contained in component (A) and/or component (B) in an amount of 1.5 to 20% by weight based on the weight of components (A) and (B) combined.

12. (new) The epoxy resin composition of claim 1 wherein the molybdenum compound (C) is zinc molybdate supported on an inorganic filler.

13. (new) A semiconductor device encapsulated with a cured product of the epoxy resin composition of claim 11.